

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



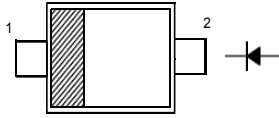
PLED

Product data sheet
Product data sheet

Surface Mount Schottky Barrier Diodes

Features

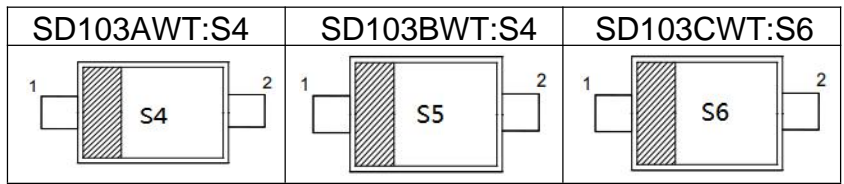
- Low Forward Voltage



MARK:

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



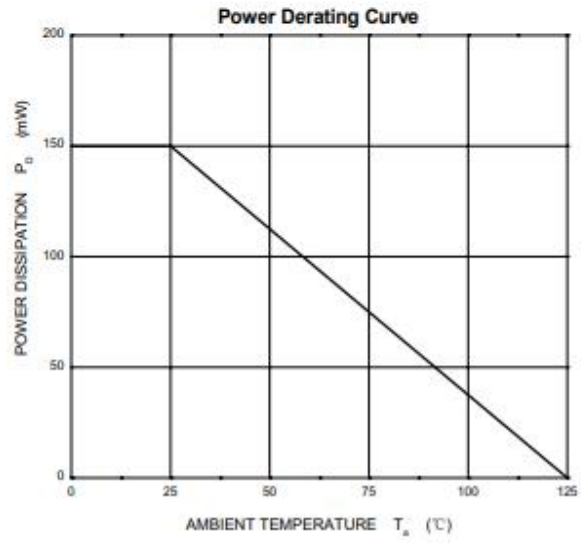
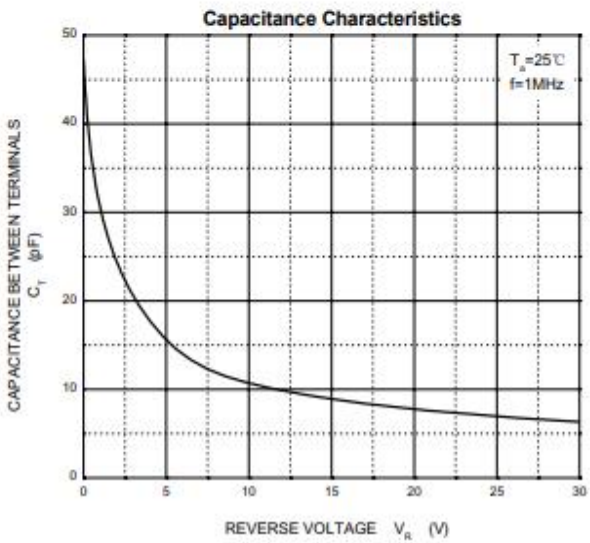
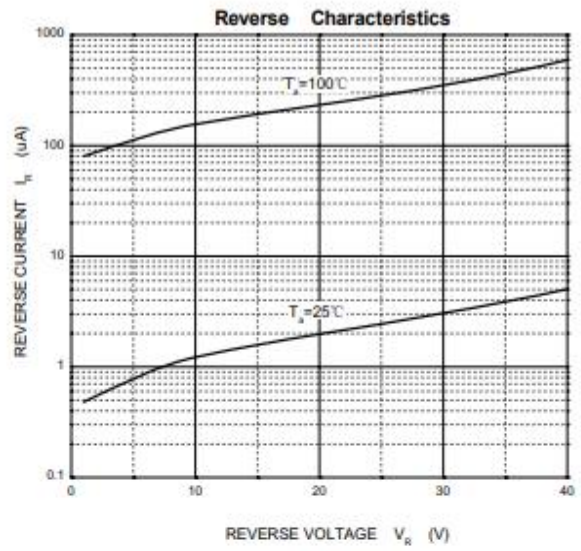
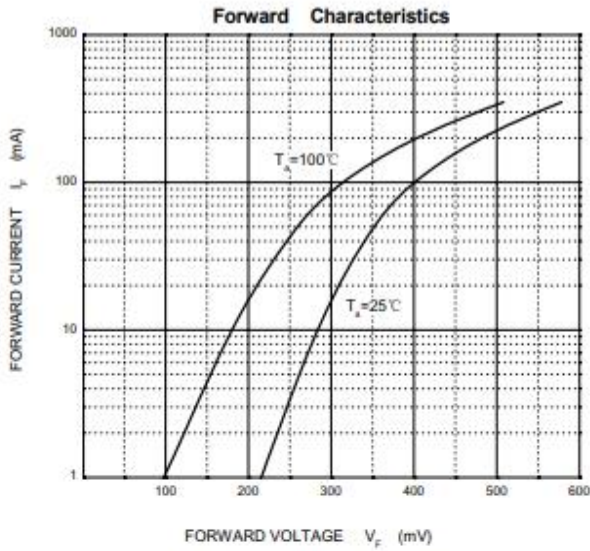
Absolute Maximum Ratings (T_a = 25 °C)

Parameter	Symbol	Value	Unit		
Peak Repetitive Reverse Voltage	V _{RRM}	SD103AWT SD103BWT SD103CWT	40 30 20	V	
Reverse Voltage		V _R	SD103AWT SD103BWT SD103CWT	40 30 20	V
Average Forward Rectified Current		I _{F(AV)}		350	mA
Non-Repetitive Peak Forward Surge Current at t = 1 s	I _{FSM}		2	A	
Power Dissipation	P _{tot}		200	mW	
Operating and Storage Temperature Range	T _j , T _{stg}		- 65 to + 125	°C	

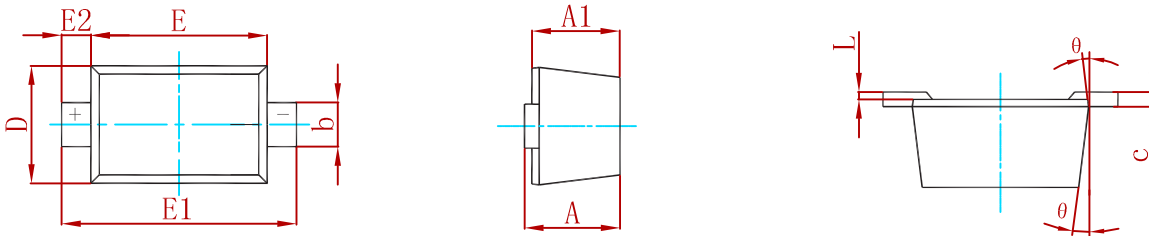
Characteristics at T_a = 25 °C

Parameter	Symbol	Min.	Typ.	Max.	Unit	
Reverse Breakdown Voltage at I _R = 10 μA	V _{(BR)R}	SD103AWT SD103BWT SD103CWT	40 30 20	- - -	V	
Reverse Leakage Current at V _R = 30V at V _R = 20 V at V _R = 10 V		I _R	- - -	- - -	5 5 5	μA
Forward Voltage at I _F = 20 mA at I _F = 200 mA		V _F	- -	- -	0.37 0.6	V
Total Capacitance at V _R = 0 V, f = 1 MHz	C _T	-	50	-	pF	
Reverse Recovery Time at I _F = I _R = 200 mA, I _{rr} = 0.1 I _R , R _L = 100 Ω	t _{rr}	-	10	-	ns	

Typical Characteristics

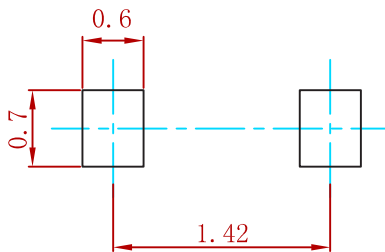


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008 REF	
L	0.010	0.070	0.001	0.003
θ	7° REF		7° REF	

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05mm.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
SD103AWT/SD103BWT/SD103CWT	SOD-523	3000

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